

PCN Number:	20200527000.1A		PCN Date:	Aug. 10, 2020							
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)										
Customer Contact:	PCN Manager	Dept:	Quality Services								
Proposed 1st Ship Date:	Aug. 28, 2020	Estimated Sample Availability:	Date provided at sample request								
Change Type:											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site						
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials						
				<input type="checkbox"/>	Wafer Fab Process						
PCN Details											
Description of Change:											
<p>Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice (Nov 10, 2020) for these newly added devices only. The proposed 1st ship date of Aug 28, 2020 still applies for the original set of devices.</p> <p>Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for selected devices listed in "Product affected" section below. Devices will remain in current assembly facilities and there will be no other piece part changes:</p>											
<table border="1"> <thead> <tr> <th>Pkg Family</th> <th>Current Wire</th> <th>Additional Wire</th> </tr> </thead> <tbody> <tr> <td>SOT-23, SOT-SC70, VSSOP</td> <td>Au, 0.9/1.0mil</td> <td>Cu, 0.96 mil</td> </tr> </tbody> </table>						Pkg Family	Current Wire	Additional Wire	SOT-23, SOT-SC70, VSSOP	Au, 0.9/1.0mil	Cu, 0.96 mil
Pkg Family	Current Wire	Additional Wire									
SOT-23, SOT-SC70, VSSOP	Au, 0.9/1.0mil	Cu, 0.96 mil									
Reason for Change:											
<p>Continuity of supply.</p> <ol style="list-style-type: none"> 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock 											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Anticipated impact on Material Declaration											
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp								
Changes to product identification resulting from this PCN:											
None											

Product Affected:			
LM26CIM5-BPB/NOPB	LM27CIM5-1HJ/NOPB	LM86CIMM/NOPB	LM95241CIMM/NOPB
LM26CIM5-DPB/NOPB	LM27CIM5-2HJ/NOPB	LM86CIMMX/NOPB	LM95241CIMM-1/NOPB
LM26CIM5-HHD/NOPB	LM27CIM5X-1HJ/NOPB	LM89-1CIMM/NOPB	LM95241CIMM-2/NOPB
LM26CIM5-NPA/NOPB	LM27CIM5X-2HJ/NOPB	LM89-1CIMMX/NOPB	LM95241CIMMX/NOPB
LM26CIM5-PHA/NOPB	LM27CIM5-ZHJ/NOPB	LM89-1DIMM/NOPB	LM95245CIMM
LM26CIM5-RPA/NOPB	LM45BIM3	LM89-1DIMMX/NOPB	LM95245CIMM/NOPB
LM26CIM5-SHA/NOPB	LM45BIM3/NOPB	LM89CIMM/NOPB	LM95245CIMM-1/NOPB
LM26CIM5-SPA/NOPB	LM45BIM3X/NOPB	LM89CIMMX/NOPB	LM95245CIMMX/NOPB
LM26CIM5-TPA/NOPB	LM45CIM3/NOPB	LM90CIMM/NOPB	LM95245CIMMX-1/NOPB
LM26CIM5-VHA/NOPB	LM45CIM3X	LM90CIMMX/NOPB	LM99-1CIMM/NOPB
LM26CIM5-VPA/NOPB	LM45CIM3X/NOPB	LM94021BIMG/NOPB	LM99CIMM/J7002180
LM26CIM5X-DPB/NOPB	LM60BIM3	LM94021BIMGX/NOPB	LM99CIMM/NOPB
LM26CIM5-XHA/NOPB	LM60BIM3/NOPB	LM94022BIMG	LM99CIMMX/NOPB
LM26CIM5X-HHD/NOPB	LM60BIM3X	LM94022BIMG/NOPB	LMT84DCKR
LM26CIM5X-NPA/NOPB	LM60BIM3X/NOPB	LM94022BIMGX/NOPB	LMT84DCKT
LM26CIM5-XPA/NOPB	LM60CIM3	LM95010CIMM/NOPB	LMT85DCKR
LM26CIM5X-PHA/NOPB	LM60CIM3/NOPB	LM95071CIMF	LMT85DCKT
LM26CIM5X-SPA/NOPB	LM60CIM3X	LM95071CIMF/NOPB	LMT86DCKR
LM26CIM5X-TPA/NOPB	LM60CIM3X/NOPB	LM95071CIMFX	LMT86DCKT
LM26CIM5X-VHA/NOPB	LM61BIM3	LM95071CIMFX/NOPB	LMT87DCKR
LM26CIM5X-VPA/NOPB	LM61BIM3/NOPB	LM95221CIMM/NOPB	LMT87DCKT
LM26CIM5X-XHA/NOPB	LM61BIM3X/NOPB	LM95221CIMMX/NOPB	LMT88DCKR
LM26CIM5X-XPA/NOPB	LM61CIM3	LM95231BIMM-1/NOPB	LMT88DCKT
LM26CIM5X-YHA/NOPB	LM61CIM3/NOPB	LM95231CIMM/NOPB	LMT89DCKR
LM26CIM5X-YPA/NOPB	LM61CIM3X/NOPB	LM95231CIMM-1/NOPB	LMT89DCKT
LM26CIM5X-YPE/NOPB	LM62BIM3/NOPB	LM95231CIMM-2/NOPB	LMT90DBZR
LM26CIM5X-ZHA/NOPB	LM62BIM3X/NOPB	LM95231CIMMX/NOPB	LMT90DBZT
LM26CIM5-YHA/NOPB	LM62CIM3/NOPB	LM95235CIMM/NOPB	LPV801DBVR
LM26CIM5-YPA/NOPB	LM62CIM3X/NOPB	LM95235CIMMX/NOPB	LPV801DBVT
LM26CIM5-YPE/NOPB	LM71CIMF	LM95235DIMM/NOPB	TLV8801DBVR
LM26CIM5-ZHA	LM71CIMF/NOPB	LM95235DIMMX/NOPB	TLV8801DBVT
LM26CIM5-ZHA/NOPB	LM71CIMFX/NOPB	LM95235EIMM/NOPB	

Qualification Data

Approved on 08/17/2015

Qualification of 0.96 mils Cu wires on SOT-SC70 Package

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMV7275MG/NOPB	Supporting QBS: LM4041 AIM3-1.2 (TL)	Supporting QBS: LM4041 AIM3-1.2 (TL)
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	-
TC	Temperature Cycle, - 65/150C	500 Cycles	1/77/0	-	-
TC	Temperature Cycle, - 65/150C	1000 Cycles	-	3/231/0	-
HTSL	High Temp Storage Bake 150C	500 Hours	1/77/0	2/154/0	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/77/0	2/154/0	1/79/0
MQ	Manufacturability (Assembly)	---	1/pass	1/pass	1/pass

- QBS: Qual By Similarity

- Qual Device LMV7275MG/NOPB is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Data

Qualification of 0.96 mils Cu wires on SOT23 Packages

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM4041 AIM3-1.2	Qual Device: LP3985IM5X-5.0	Qual Device: LMC7101AIM5NOPB	Qual Device: LM431CCM3NOPB
PC	PreCon Level 1	Level 1- 260C	3/693/0	3/462/0	3/693/0	3/462/0
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	3/231/0	-	3/231/0	-
AC	Autoclave 121C	96HRS	3/231/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0

HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	1/77/0	-	1/77/0	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Data

Qualification of 0.96 mils Cu wires VSSOP Packages

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMV852MMX	Qual Device: LMC6482IMM
PC	PreCon Level 1	Level 1-260C	3/462/0	3/462/0
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	-	-
AC	Autoclave 121C	96HRS	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

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